Connector for microSD™ Card (Push-push Type)

SCHA Series



SD Memory Card

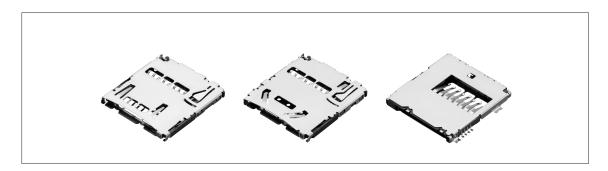
microSD™ Card For SIM Card 8pins

Stick Micro™

Combine Type

For W-SIM

Compact low-profile type most suitable for mobile phones.



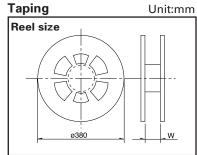
Typical Specifications

1 ypical Specifications						
Items			Specifications			
Structure	Applicable media		microSD™ Card			
	Mounting t	уре	Surface mounting type			
	Mounting style		Standard mount/ Reverse mount			
	Media ejection structure		Push-push type			
	Operating temperature range		−20°C to +70°C			
	Voltage proof		500V AC 1minute			
Performance	Insulation resistance (Initial)		1,000MΩ min.			
1 enormance	Contact resistance (Initial)	Connector contacts	100m Ω max.			
		Detection switch	500 m Ω max.			
	Insertion and removal cycle		10,000cycles			

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
	Standard mount	With switch	0	Taping	SCHA4B0100	1
Push-push type		With switches and fly-out protection.			SCHA4B0400	2
	Reverse mount	With switch			SCHA5B0200	3

Packing Specifications



Product No.	Number of packages (pcs.)			Reel width	Tape width	Export package	
	1 reel	1 case /Japan	1 case /export packing	W (mm)	(mm)	measurements (mm)	
SCHA4B0100	2,000	6,000	12,000	24.4	24	403×403×249	
SCHA4B0400	2,000	0,000	12,000				
SCHA5B0200	1,500	4,500	9,000				



Note

Please place purchase orders per minimum order unit N (integer).

Dimensions Standard mount

Unit:mm

SD Memory Card

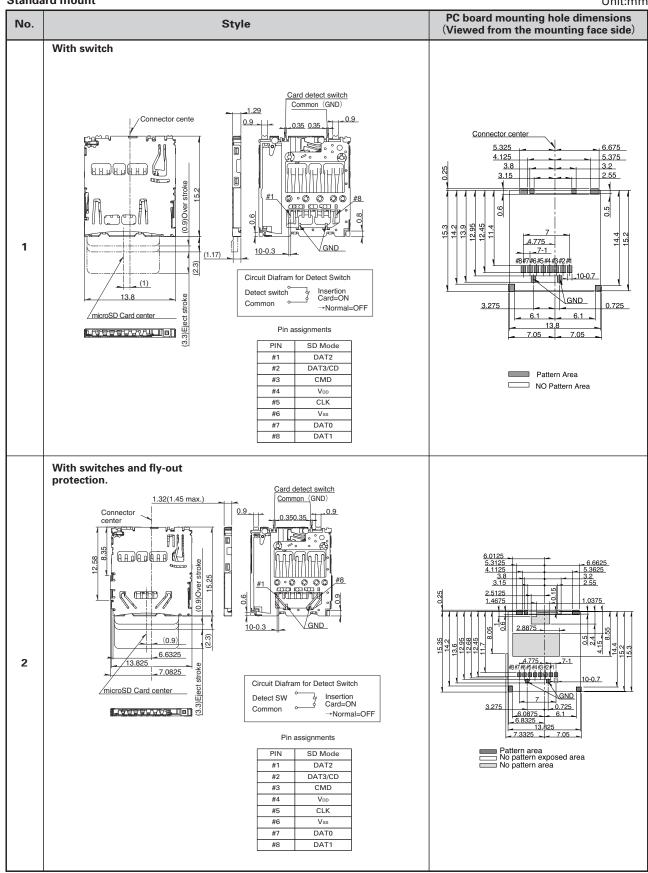
For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

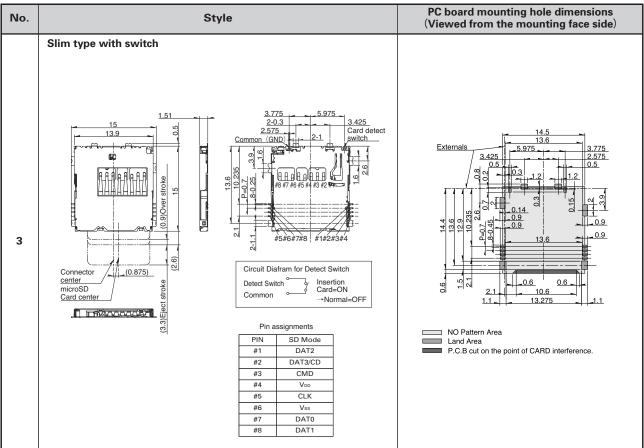
For W-SIM





Dimensions Reverse mount

Unit:mm



For SD Memory Card

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List of Varieties

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

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Combine Type

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Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
	SCDA9A0400		Push-push type	Standard mount	Inner tail Card eject stroke 5mm	0		527
	SCDA8A0201	The state of the s			Inner tail Card eject stroke 8mm			
	SCDA7A0101				Card eject stroke 8mm		0	
SD Memory Card	SCDA7A0200					1.5		
Multi-MediaCard™	SCDA7A1201	1				1.8		
	SCDAAA0100	C. Million		Reverse mount	Outer tail	0		
	SCDAAA0601					1.8		
	SCHA4B0100			Standard mount	With switch	0	0	
	SCHA4B0400				With switches and fly-out protection.			532
	SCHA5B0200			Reverse mount	With switch		0	
microSD™	SCHB1A0205		Manual insertion/ removal	Standard	Hinge cover type Without switch			535
Card	SCHB1B0100	11000			Hinge cover type With switch			
	SCHD1A0101			mount	Header type			537
	SCHD3A0100							<i>331</i>
	SCHH1D0100				Adapter			539

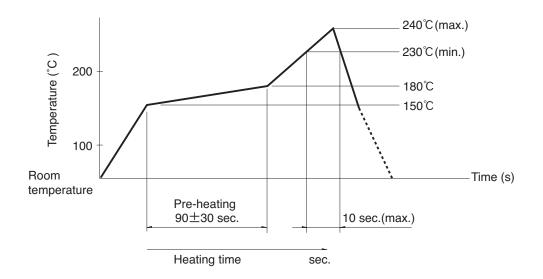
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2ϕ CA (K) or CC (T) at soldering portion.
- 3. Temperature profile



Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

- 1. Connector hamdling precautions
- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If youwash it, it may be cause deterioration of mechanically and electrically.

If washing is necessary, pleasemake contact with us beforehand.

2. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformayion or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3. When soldering, do not use water soluble flux because this may corrode the product.

4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6.Please do not solder at the ejector pushing position.

- 7.To prevent contact disturbance by the sulfuration or oxidation of the conyact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.
- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorinate gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.
- 8.Don't push or hold down the metal cover of the connector, otherwise there is a possibolity that the card would not be ejected or influences to other function.
- 9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.
- · Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- · Establish CR accumulation circuit.
- 10. This product does not operate normally when the card which does not conform to the specification is used occasionally.

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